Abstract

A silver paste consisting of

(i) 5 to 15 wt% of at least one organic solvent,

(ii) 75 to 90 wt% of silver particles,

(iii) 5 to 10 wt% of a curable epoxy resin / hardener system, and

(iv) 0 to 2 wt% of at least one constituent other than constituents (i) to (iii),

wherein the curable epoxy resin / hardener system (iii) consists of no or at least one non-elastomer-modified epoxy resin (iiia), at least one elastomer-modified epoxy resin (iiib), and at least one hardener (iiic),

wherein the weight ratio of epoxy resins (iiia) and (iiib) is ≤1.0, and wherein the at least one hardener (iiic) is selected from the group consisting of amine hardeners (iiic1) or from the group consisting of anhydride hardeners (iiic2). The silver paste can be used as interconnection material in electronics applications.